



# SPN8862

## N-Channel Enhancement Mode MOSFET

### DESCRIPTION

The SPN8862 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching is required.

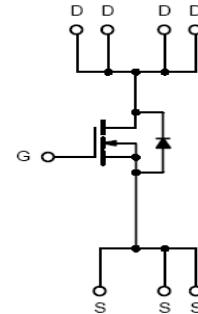
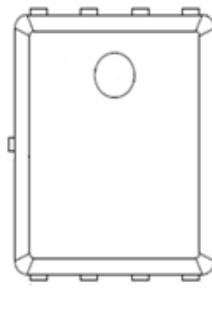
### APPLICATIONS

- DC/DC Converter
- Load Switch
- Synchronous Buck Converter

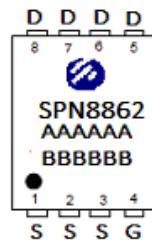
### FEATURES

- ◆ 60V/15A,  $R_{DS(ON)}=12m\Omega$  @  $V_{GS}=10V$
- ◆ 60V/10A,  $R_{DS(ON)}=15m\Omega$  @  $V_{GS}=4.5V$
- ◆ Super high density cell design for extremely low  $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ PPAK5x6-8L package design

### PIN CONFIGURATION (PPAK5x6-8L)



### PART MARKING



A : Lot Code  
B : Date Code  
(YY/MM/DD)



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### PIN DESCRIPTION

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

### ORDERING INFORMATION

Part Number	Package	Part Marking
SPN8862DN8RGB	PPAK5x6-8L	SPN8862

※ SPN8862DN8RGB : 13" Tape Reel ; Pb – Free ; Halogen – Free

### ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	V
Gate –Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current(T <sub>J</sub> =150°C)	T <sub>C</sub> =25°C	ID	A
	T <sub>C</sub> =70°C		
Pulsed Drain Current	I <sub>DM</sub>	230	A
Avalanche Current	I <sub>AS</sub>	38	A
Power Dissipation	T <sub>C</sub> =25°C	P <sub>D</sub>	W
	T <sub>A</sub> =70°C		
Operating Junction Temperature	T <sub>J</sub>	-55/150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Case	R <sub>θJC</sub>	1.5	°C/W



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### ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, ID=250uA	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , ID=250uA	1.0		2.5	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V			1	
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			5	uA
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥5V, V <sub>GS</sub> =10V	60			A
Drain-Source On-Resistance	R <sub>D(on)</sub>	V <sub>GS</sub> =10V, ID=10A		10	12	
		V <sub>GS</sub> =4.5V, ID=8A		12	15	mΩ
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =10V, ID=6A		11.8		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =1A, V <sub>GS</sub> =0V			1	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =4.5V ID=12A		24		
Gate-Source Charge	Q <sub>gs</sub>			6.9		
Gate-Drain Charge	Q <sub>gd</sub>			10		nC
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V f=1MHz		3200		
Output Capacitance	C <sub>oss</sub>			210		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			145		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V, ID=2A, V <sub>GEN</sub> =10V R <sub>G</sub> =3.3Ω		20		
	t <sub>r</sub>			4		
Turn-Off Time	t <sub>d(off)</sub>			84.5		
	t <sub>f</sub>			6.5		nS



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### TYPICAL CHARACTERISTICS

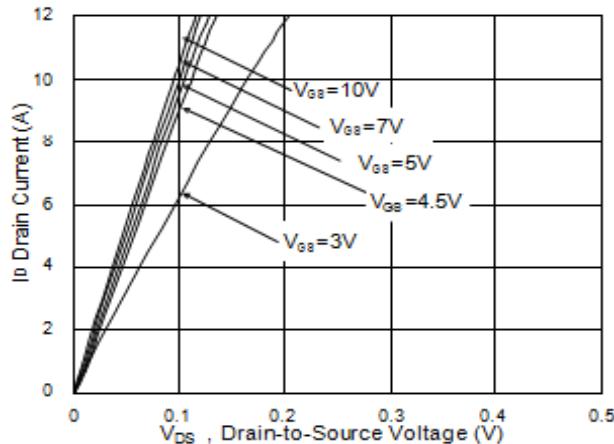


Fig. 1 Typical Output Characteristics

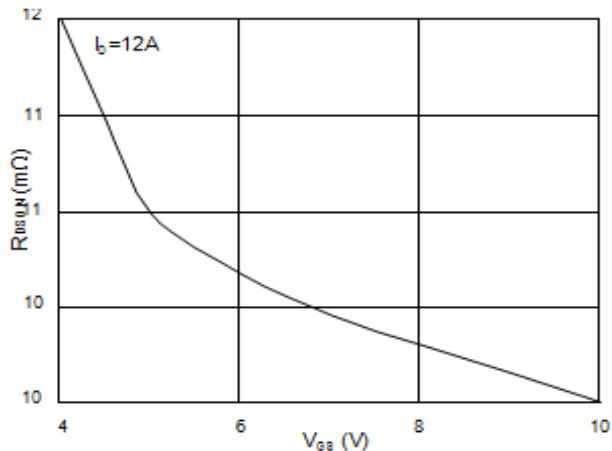


Fig. 2 On-Resistance vs. Gate Voltage

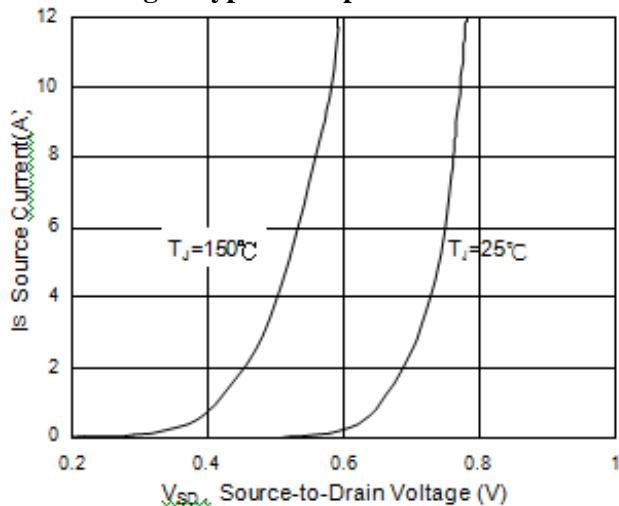


Fig. 3 Forward Characteristics  
Reverse Diodes

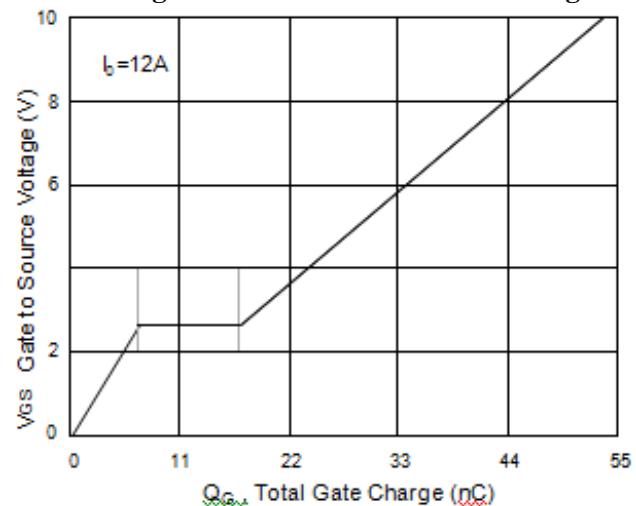


Fig. 4 Gate Charge Characteristics

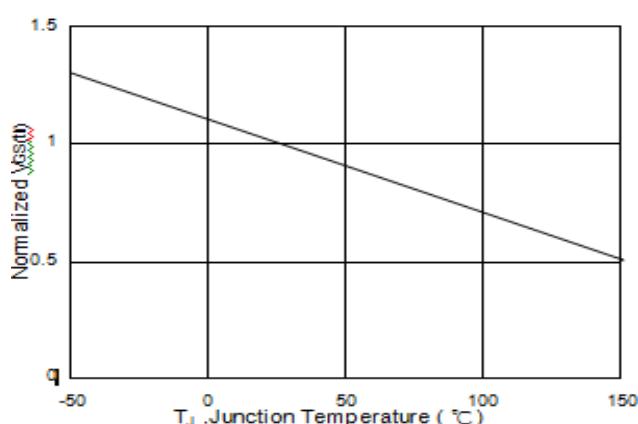


Fig. 5  $V_{GS}$  vs. Junction Temperature

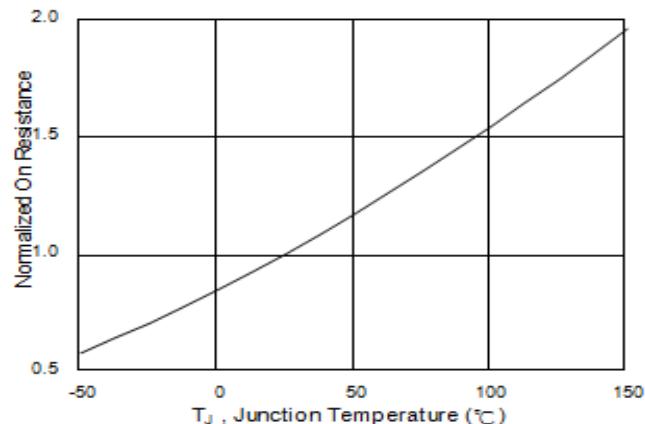


Fig. 6 On-Resistance vs. Temperature



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### TYPICAL CHARACTERISTICS

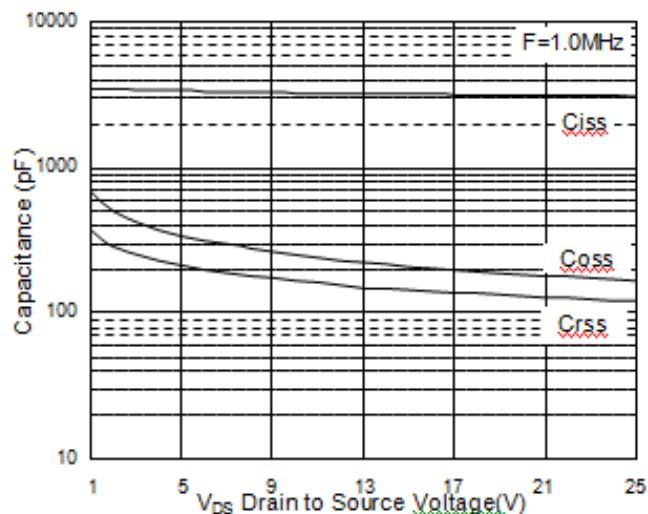


Fig. 7 Typical Capacitance Characteristics

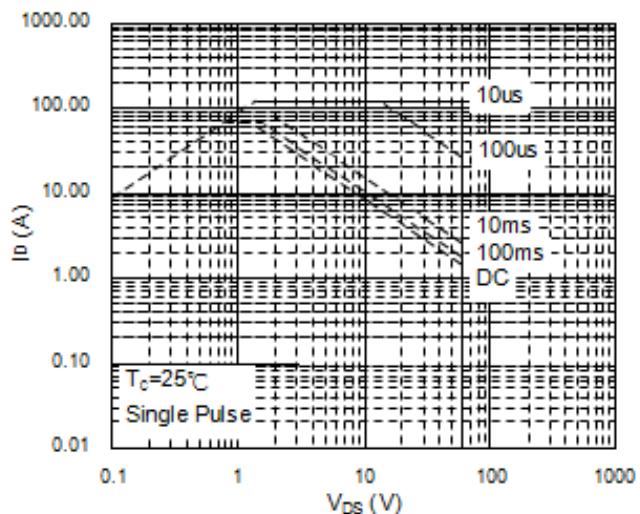


Fig. 8 Maximum Safe Operation Area

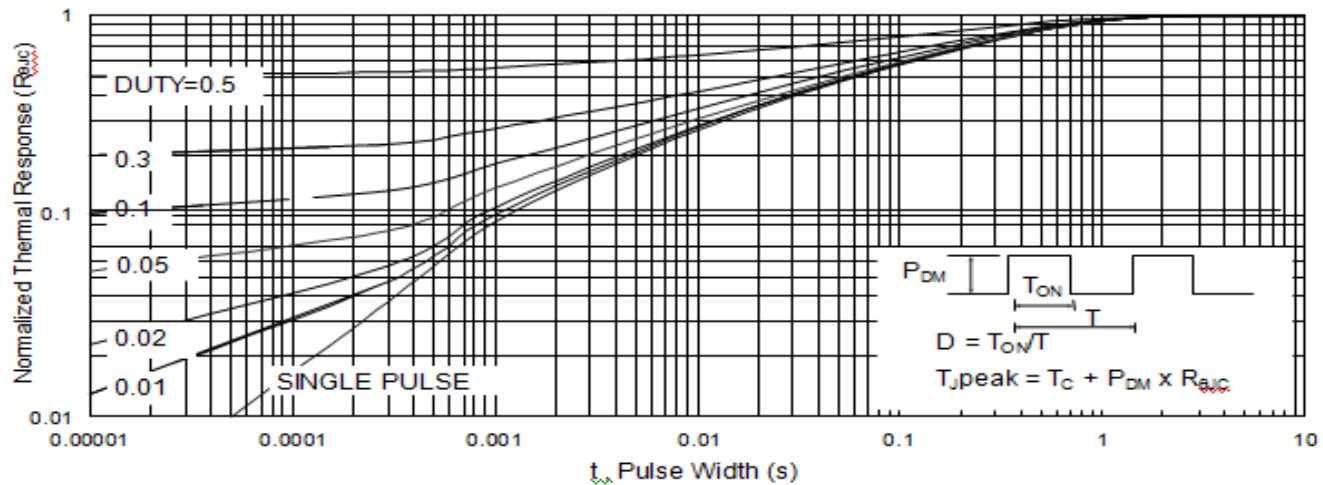


Fig. 9 Effective Transient Thermal Impedance

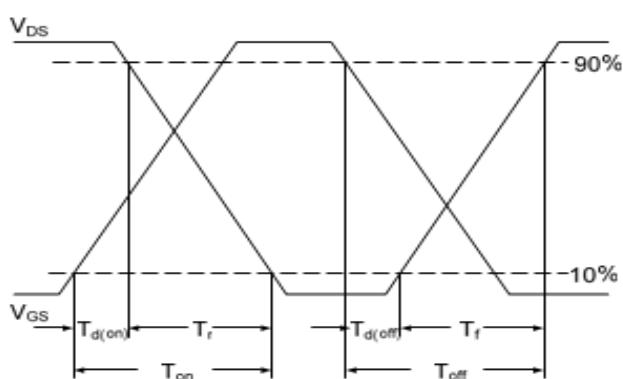


Fig. 10 Switching Time Waveform

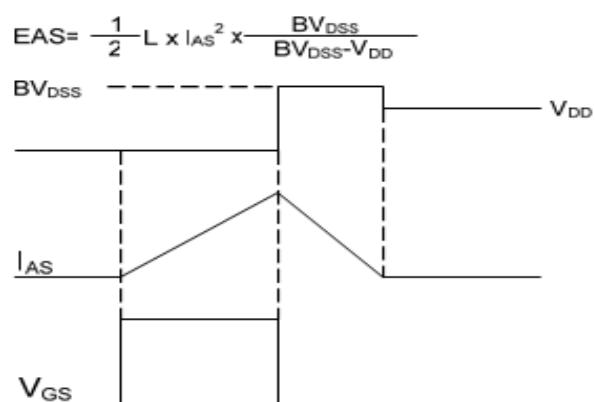


Fig. 11 Unclamped Inductive Waveform



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